

Filename: PMP5863\_REVC\_SCH\_bom.xls

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## IP5863\_REVC\_SCH BOM

COUNT	RefDes	Value	Description	Size	Part Number
4	C1, C2, C7, C8	22uF	Capacitor, Cerami	1210	Std
1	C10	470pF	Capacitor, Cerami	0603	Std
1	C11	0.82uF	Capacitor, Cerami	0603	Std
2	C12, C17	1uF	Capacitor, Cerami	1210	Std
2	C13, C18	5pF	Capacitor, Cerami	0603	Std
2	C14, C19	10uF	Capacitor, Cerami	1206	Std
2	C15, C20	0.1uF	Capacitor, Cerami	0805	Std
2	C16, C21	0.01uF	Capacitor, Cerami	0603	Std
0	C3	Open	Capacitor, multi p	Multi sizes	Engineering Only
1	C4	10uF	Capacitor, Cerami	1210	Std
1	C5	1uF	Capacitor, Cerami	1210	Std
2	C6, C9	0.1uF	Capacitor, Cerami	0603	Std
2	D1, D2	B260A-13-F	Diode, Schottky B	SMA	B260A-13-F
0	D3	OPEN	Diode, Zener, 18- <sup>v</sup>	DO-41	1N47xxA
1	J1	ED555/2DS	Terminal Block, 2-	0.27 x 0.25"	ED555/2DS
1	J3	RAPC 722	Connector, 2.1mm	0.57 x 0.35 inch	RAPC 722
12	J5, J6, J7, J8, J10, J	PEC02SAAN	Header, Male 2-pi	0.100 inch x 2	PEC02SAAN
2	J9, J18	PEC05DAAN	Header, Male 2x5-	0.100 inch x 5 X 2	PEC05DAAN
1	L1	150uH	Inductor, SMT, 1.8	0.484 x 0.484 inch	MSD1278 -154L
1	R1	9.76k	Resistor, Chip, 1/1	0603	Std
2	R10, R15	187k	Resistor, Chip, 1/1	0603	Std
2	R11, R13	340k	Resistor, Chip, 1/1	0603	Std
2	R12, R6	619k	Resistor, Chip, 1/1	0603	Std
	R16	52.3k	Resistor, Chip, 1/1	0603	Std
1	R18	100k	Resistor, Chip, 1/1	0603	Std
1	R2	412K	Resistor, Chip, 1/1	0603	Std
1	R3	1.13k	Resistor, Chip, 1/1	0603	Std
1	R4	44.2k	Resistor, Chip, 1/1	0603	Std
1	R5		49.9 Resistor, Chip, 1/1	0603	Std
2	R7	52.3K	Resistor, Chip, 1/1	0603	Std
2	R8, R17	66.5k	Resistor, Chip, 1/1	0603	Std
2	R9, R14	562k	Resistor, Chip, 1/1	0603	Std

3 S1	OPEN	Switch, SPDT, Slic 0.457 x 0.157 inch	EG1218
3 S2, S3	EG1218	Switch, SPDT, Slic 0.457 x 0.157 inch	EG1218
4 Screws		4-40 Screw for Standoffs	Std
4 Standoffs		3479 Standoff RD 4-40 0.375"	3479
8 TP1, TP2, TP4, TP5		5000 Test Point, Red, 10.100 x 0.100 inch	5000
3 TP3, TP6, TP9		5001 Test Point, Black, 0.100 x 0.100 inch	5001
1 U1	TPS54260DGQ	IC, 3.5V to 60V Inj MSOP-10	TPS54260DGQ
1 U2	TPS7A3001DGN	IC, -3V to -36V, -2 MSOP-8	TPS7A3001DGN
1 U3	TPS7A4901DGN	IC, VIN 3V to 35V, HTSSOP	TPS7A4901DGN
4 --		Shunt, 100-mil, Bl: 0.1	929950-00

- Notes:
1. These assemblies are ESD sensitive, ESD precautions shall be observed.
  2. These assemblies must be clean and free from flux and all contaminants.  
Use of no clean flux is not acceptable.
  3. These assemblies must comply with workmanship standards IPC-A-610 Class 2.
  4. Ref designators marked with an asterisk (\*\*\*) cannot be substituted.  
All other components can be substituted with equivalent MFG's components.

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